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| <b>PATENT ASSIGNMENT COVER SHEET</b> |
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT7013572

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|---|------------------------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                     |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                         |
| <b>CONVEYING PARTY DATA</b>   |                                    |
| <b>Name</b>   | <b>Execution Date</b>              |
| CHIA-HAO HSU  | 01/07/2020                         |
| TAI-YU CHEN   | 01/07/2020                         |
| SHIANN-TSONG TSAI   | 01/08/2020                         |
| HSING-CHIH LIU  | 01/08/2020                         |
| YAO-PANG HSU  | 01/07/2020                         |
| CHI-YUAN CHEN   | 01/07/2020                         |
| CHUNG-FA LEE  | 01/07/2020                         |
| <b>RECEIVING PARTY DATA</b>   |                                    |
| <b>Name:</b>  | MEDIATEK INC.                      |
| <b>Street Address:</b>  | NO. 1, DUSING RD. 1ST              |
| <b>Internal Address:</b>  | SCIENCE-BASED INDUSTRIAL PARK      |
| <b>City:</b>  | HSIN-CHU 300                       |
| <b>State/Country:</b>   | TAIWAN                             |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                    |
| <b>Property Type</b>  | <b>Number</b>                      |
| <b>Application Number:</b>  | 16802576                           |
| <b>CORRESPONDENCE DATA</b>  |                                    |
| <b>Fax Number:</b>  | (617)646-8646                      |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |                                    |
| <b>Phone:</b>   | 6176468000                         |
| <b>Email:</b>   | stacey.appleton@wolfgreenfield.com |
| <b>Correspondent Name:</b>  | WOLF GREENFIELD & SACKS, P.C.      |
| <b>Address Line 1:</b>  | 600 ATLANTIC AVENUE                |
| <b>Address Line 4:</b>  | BOSTON, MASSACHUSETTS 02210        |
| <b>ATTORNEY DOCKET NUMBER:</b>  | M1295.70394US00                    |
| <b>NAME OF SUBMITTER:</b>   | STACEY L. APPLETON                 |
| <b>SIGNATURE:</b>   | /Stacey L. Appleton/               |
| <b>DATE SIGNED:</b>   | 11/09/2021                         |

**Total Attachments: 14**

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:**

**SEMICONDUCTOR PACKAGE HAVING IMPROVED THERMAL INTERFACE  
BETWEEN SEMICONDUCTOR DIE AND HEAT SPREADING STRUCTURE**

As the below named inventor, I hereby declare that:  
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- United States application number \_\_\_\_\_ filed on \_\_\_\_\_, or
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The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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In consideration of the payment by MEDIATEK INC. having a postal address of

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(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No MTKP3451USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chia-Hao Hsu**

Date:

2020.01.07.

Signature:

Chia-Hao Hsu

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Docket No MTKP3451USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Tai-Yu Chen**

Date: 2020.01.07.

Signature: Tai-Yu Chen

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Docket No MTKP3451USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shiann-Tsong Tsai**

Date: 2020.01.08

Signature: Shiann Tsong Tsai



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Docket No MTKP3451USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Hsing-Chih Liu

Date: 2020.1.8

Signature: Hsing Chih Liu

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

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Docket No MTKP3451USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yao-Pang Hsu**

Date:

2020.01.07

Signature:

Yao Pang Hsu

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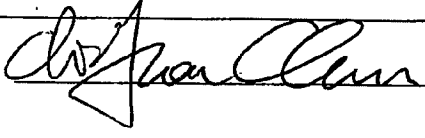
LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chi-Yuan Chen**

Date:

2020.01.07

Signature:



**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chung-Fa Lee**

Date: 2020.1.7

Signature: Chung-Fa Lee